

CLAIMS

1. A water-permeable adhesive tape for processing semiconductor wafers and/or semiconductor related materials, comprising at least one base film and an adhesive, wherein said at least one base film possesses perforations and has a cavity ratio of 3.0 to 90%.
2. The water-permeable adhesive tape according to claim 1, wherein the base film comprises a synthetic resin or a non-woven fabric.
3. The water-permeable adhesive tape according to claim 1 or 2, wherein the size of the perforations is from 0.001 to 3.0 mm².
4. The water-permeable adhesive tape according to any of claims 1 to 3, wherein the adhesive comprises a rubber- or acrylic-based adhesive.
5. The water-permeable adhesive tape according to any of claims 1 to 4, wherein the adhesive is pressure-sensitive, light-sensitive and/or heat-sensitive.
6. The water-permeable adhesive tape according to any of claims 1 to 5, having an elongation of more than 10%.
7. The water-permeable adhesive tape according to any of claims 1 to 6, having a tensile strength of more than 0.1 N/20 mm.
8. The water-permeable adhesive tape according to any of claims 1 to 7, having an adhesive strength of 0.15 to 10 N/20 mm.